

NMC6504 4096-Bit (4096 × 1) Static RAM

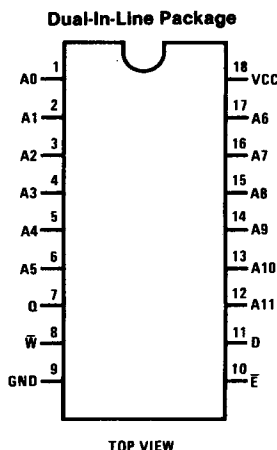
General Description

The NMC6504 is a static CMOS random access read/write memory organized as 4096 words of 1 bit each. This device is fabricated with National Semiconductor's silicon-gate CMOS technology and is fully compatible to the TTL environment. Synchronous operation is provided by on-chip address, data, and write latches. The ENABLE input serves as the device strobe controlling the latching functions. The TRI-STATE® output, in conjunction with the ENABLE input, allows easy memory expansion.

Features

- Industry standard pinout
- Low data retention voltage — 2V
- Low speed/power product
- TTL compatible — all inputs and outputs
- TRI-STATE® outputs for bus operation
- High output drive
- High noise immunity
- Military temperature range available
- On-chip address registers (latches)
- Common I/O — high density packaging
- Output data latches
- Input data latches
- Select latch for microprocessor interface

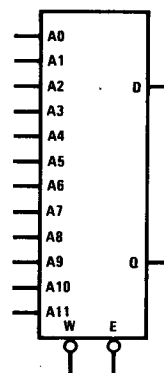
Connection Diagram



Order Number NMC6504J-2, NMC6504J-9
or NMC6504J-5
See NS Package J18A

Order Number NMC6504N-5
See NS Package N18A

Logic Symbol



Pin Names

A0-A11	Address Inputs
$\bar{E}$	Chip Enable
$\bar{W}$	Write Enable
D	Data Input
Q	Data Output

Functional Description

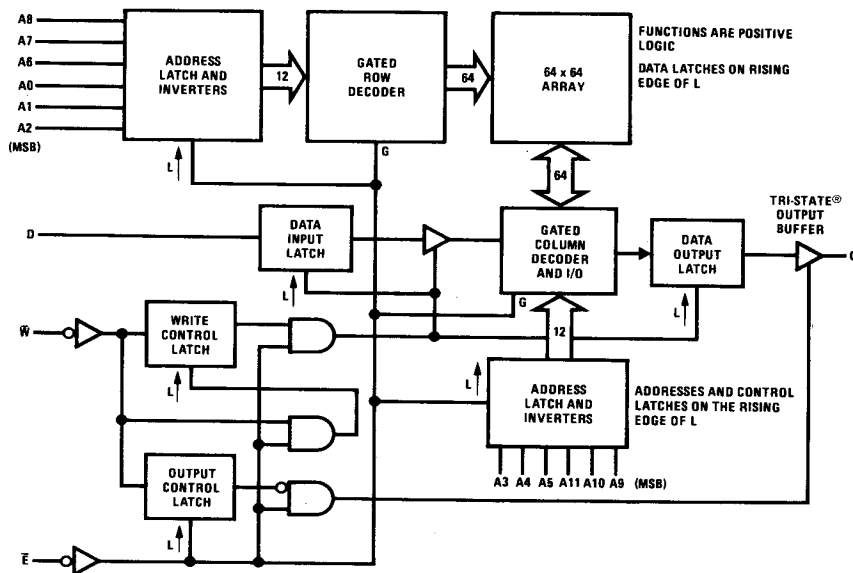
An NMC6504 memory cycle is initiated by the falling edge of the ENABLE ($\bar{E}$) input which latches the address information into the on-chip registers. On-chip latches allow selection of a read, early write, or read-modify-write cycle as a function of the ENABLE and WRITE ($\bar{W}$) input levels and timing. Data output is enabled by the falling edge of the ENABLE input and disabled by the rising edge except when performing an early write cycle. The input and output data latches are transparent except during the write pulse (not the WRITE input).

When performing a read cycle a minimum ENABLE LOW time is required to assure valid data at the output. This minimum LOW time is defined as the enable access time. A minimum ENABLE HIGH time is required to return the columns to the HIGH state and to precharge the sense amplifiers in preparation of the next cycle.

An early write cycle is performed by preceding the ENABLE with the HIGH to LOW transition of the WRITE input. The WRITE input level is latched, and set-up and hold times must be met. The data output is not enabled during an early write cycle. The input data set-up and hold times are referenced to the leading edge of the write pulse, which is initiated by the falling edge of the ENABLE input and terminated by the rising edge of the ENABLE.

A read-modify-write cycle is performed as a read cycle, for the enable access time, followed by the write pulse which is initiated by the falling edge of the WRITE input and terminated by the rising edge of either the ENABLE or WRITE input, whichever occurs first. The input data set-up and hold times are referenced to the falling edge of the WRITE input. Data is latched when the WRITE input goes LOW, allowing the modified data to be written into the memory while continuing to read the original data.

Block Diagram



Absolute Maximum Ratings

Supply Voltage VCC	7V
Voltage at Any Pin	-0.3V to VCC +0.3V
Storage Temperature Range	-65°C to +150°C
Package Dissipation	500 mW
Lead Temperature (Soldering, 10 seconds)	300°C

Operating Range

	Min	Max
Supply Voltage		
NMC6504-9	4.5V	5.5V
NMC6504-2	4.5V	5.5V
NMC6504-5	4.75V	5.25V
Temperature		
NMC6504-9	-40°C	85°C
NMC6504-2	-55°C	125°C
NMC6504-5	0°C	75°C

DC Electrical Characteristics over the operating range, unless otherwise noted

Symbol	Parameter	Conditions	NMC6504-9, NMC6504-2		NMC6504-5		Units
			Min	Max	Min	Max	
VCCDR	Data Retention Supply Voltage	VI = VCC, GND	2.0		2.0		V
ICCSB	Standby Supply Current			50		500	μA
ICCOP*	Operating Supply Current	f = 1 MHz, IO = 0, VI = VCC or GND		10		10	mA
ICCDR	Data Retention Supply Current	VCC = 3.0V, IO = 0, VI = VCC or GND		25		500	μA
II	Input Leakage Current	VI = VCC, GND	-1.0	+1.0	-10	+10	μA
VIL	Input Low Voltage		-0.3	0.8	-0.3	0.8	V
VIH	Input High Voltage		VCC - 2.0	VCC + 0.3	VCC - 2	VCC + 0.3	V
IOZ	Output Leakage Current	VI = VCC, GND	-1.0	+1.0	-10	+10	μA
VOL	Output Low Voltage	IOL = 2.0 mA		0.4		0.45	V
VOH	Output High Voltage	IOH = -1.0 mA	2.4		2.4		V
CI	Input Capacitance	f = 1 MHz		8		8	pF
CO	Output Capacitance	f = 1 MHz		10		10	pF

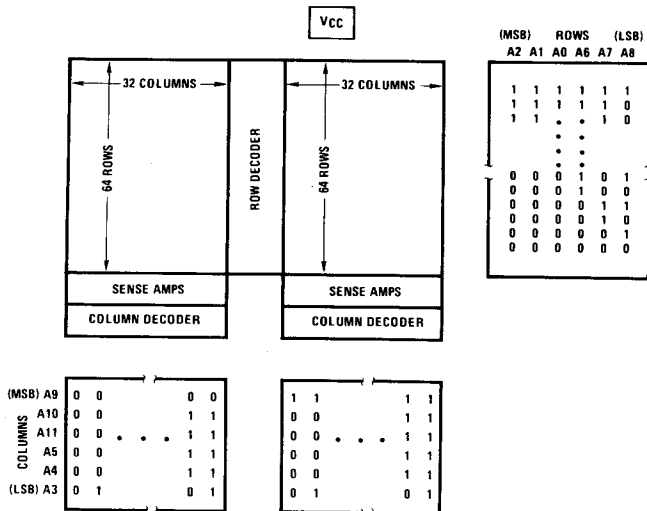
* ICCOP is proportional to operating frequency.

AC Test Conditions

Input Rise and Fall Times: ≤20 ns

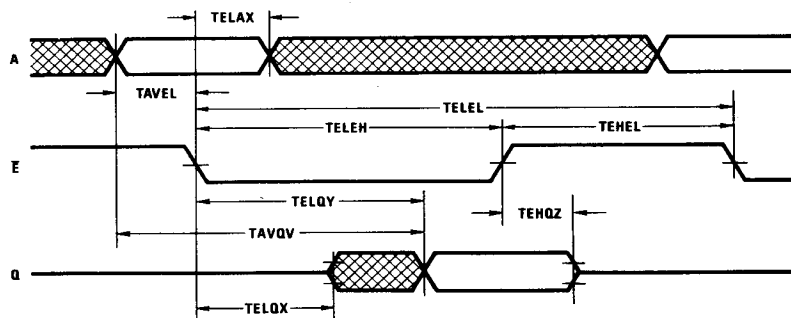
All Timing Reference Levels: 1/2 VCC

Output Load: 1 TTL Load, 50 pF

NMC6504 Bit Map and Address Decoding

Read Cycle AC Electrical Characteristics over the operating range

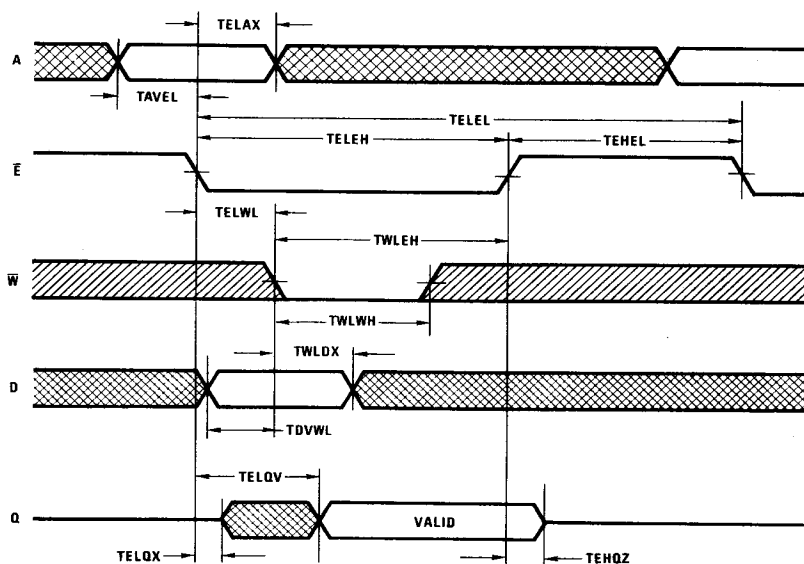
Symbol	Parameter	NMC6504-9, NMC6504-2		NMC6504-5		Units
		Min	Max	Min	Max	
TAVEL	Address Set-up Time	20		20		ns
TELAX	Address Hold Time	50		50		ns
TELQV	Enable Access Time		300		350	ns
TAVQV	Address Access Time		320		370	ns
TELEH	Enable ($\bar{E}$) Minimum Low Time	300		350		ns
TELEL	Read or Write Cycle Time	420		500		ns
TEHEL	Enable ($\bar{E}$) Minimum High Time	120		150		ns
TELQX	Output Enable from Enable ($\bar{E}$)		100		100	ns
TEHQZ	Output Disable from Enable ($\bar{E}$)		100		100	ns

Read Cycle Waveforms

Write Cycle AC Electrical Characteristics over the operating range

Symbol	Parameter	NMC6504-9, NMC6504-2		NMC6504-5		Units
		Min	Max	Min	Max	
TAVEL	Address Set-up Time	20		20		ns
TELAX	Address Hold Time	50		50		ns
TWLWH	Write Pulse Width ($\bar{W}$ Low)	80		100		ns
TELEL	Read or Write Cycle Time	420		500		ns
TELEH	Enable ($\bar{E}$) Minimum Low Time	300		350		ns
TDVWL	Data Set-up Time	0		30		ns
TEHEL	Enable ($\bar{E}$) Minimum High Time	120		150		ns
TWLDX	Data Hold Time	80		100		ns
TELWH	Write Pulse Width ($\bar{E}$ and $\bar{W}$ Low)	80		100		ns
TELWL	Early Write Output Hi-Z Time	0		0		ns
TWLEH	Write Pulse Width ($\bar{W}$ and $\bar{E}$ Low)	200		250		ns
TELQX	Output Enable from $\bar{E}$		100		100	ns
TELQV	Enable Access Time		300		350	ns
TEHQZ	Output Disable from $\bar{E}$		100		100	ns

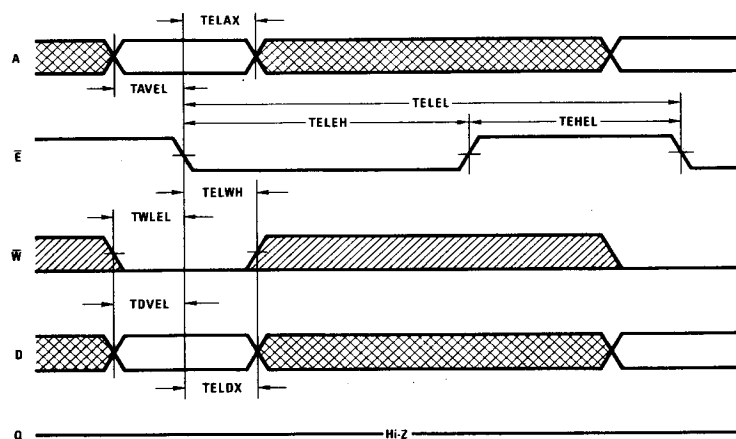
Write Cycle Waveforms



Early Write Cycle AC Electrical Characteristics over the operating range

Symbol	Parameter	NMC6504-9, NMC6504-2		NMC6504-5		Units
		Min	Max	Min	Max	
TAVEL	Address Set-up Time	20		20		ns
TELAX	Address Hold Time	50		50		ns
TELWH	Write Pulse Width ($\bar{E}$ and $\bar{W}$ Low)	80		100		ns
TDVEL	Early Write Data Set-up Time	0		30		ns
TELEH	Enable ($\bar{E}$) Minimum Low Time	300		350		ns
TWLEL	Early Write Set-up Time	0		0		ns
TEHEL	Enable ($\bar{E}$) Minimum High Time	120		150		ns
TELDX	Early Write Data Hold Time	80		100		ns
TELEL	Read or Write Cycle Time	420		500		ns

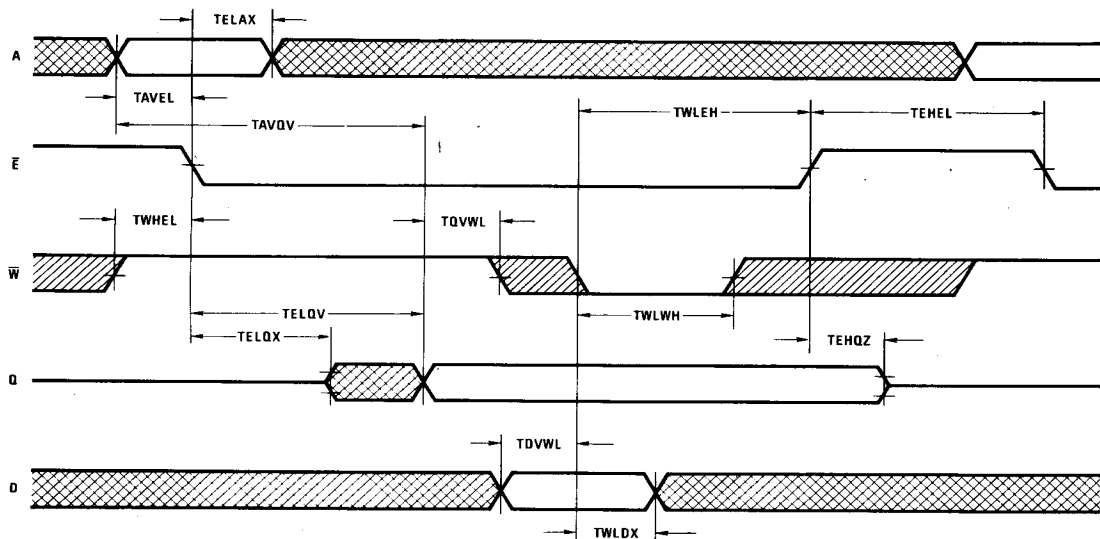
Early Write Cycle Waveforms



Read-Modify-Write Cycle AC Electrical Characteristics over the operating range

Symbol	Parameter	NMC6504-9, NMC6504-2		NMC6504-5		Units
		Min	Max	Min	Max	
TAVEL	Address Set-up Time	20		20		ns
TELAX	Address Hold Time	50		50		ns
TELQV	Enable Access Time		300		350	ns
TAVQV	Address Access Time		320		370	ns
TEHEL	Enable ($\bar{E}$) Minimum High Time	120		150		ns
TWHEL	$\bar{W}$ Read Mode Set-up Time	0		0		ns
TWLEH	Write Pulse Width ($\bar{W}$ and $\bar{E}$ Low)	200		250		ns
TQVWL	Data Valid to Write Time	0		0		ns
TWLWH	Write Pulse Width ($\bar{W}$ Low)	80		100		ns
TWLDX	Data Hold Time	80		100		ns
TELQX	Output Enable from Enable ($\bar{E}$)		100		100	ns
TEHQZ	Output Disable from Enable ($\bar{E}$)		100		100	ns
TDVWL	Data Set-up Time	0		30		ns

Read-Modify-Write Cycle Waveforms



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